

Pb RoHS

General Description

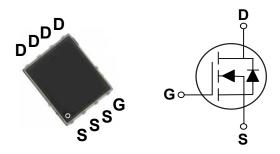
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
60 V	1.6 mΩ	236 A

Features

- $R_{DS(ON)} \leq 1.6m\Omega @V_{GS} = 10V$
- Fast Switching
- Improved dv/dt Capability
- Green Device Available

PPAK5X6 Pin Configuration



Applications

Synchronous Rectification in SMPS

Absolute Maximum Ratings T _J =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units			
V _{DS}	Drain-Source Voltage	60	V			
V _{GS}	Gate-Source Voltage	±20	V			
۱ _D	Drain Current - Continuous (T _c =25°C)	236	А			
I _{DM}	Drain Current - Pulsed (NOTE 1)	400	А			
IAS	Single Pulse Avalanche Current (L=0.1mH)	60	А			
EAS	Single Pulse Avalanche Energy (L=0.1mH)	180	mJ			
P _D	Power Dissipation (T _C =25°C)	89	W			
TJ	Operating Junction Temperature	150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		NG1P6				

Thermal Characteristics

Symbol	Parameter Rating		Unit	
R _{θJA}	Thermal Resistance Junction to Ambient	50	°C/W	
$R_{ extsf{ heta}JC}$	Thermal Resistance Junction to Case	1.4	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			1.6	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2		4	V
gfs	Forward Transconductance	V _{DS} =5V , I _D =20A		75		S

Dynamic and switching Characteristics (NOTE 3)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			85		
Q_gs	Gate-Source Charge	V_{DS} =30V , V_{GS} =10V , I_{D} =20A		16		nC
Q_{gd}	Gate-Drain Charge			19		
$T_{d(on)}$	Turn-On Delay Time			20		
T _r	Rise Time	V _{DS} =30V , V _{GS} =10V ,		15		nS
$T_{d(off)}$	Turn-Off Delay Time	R_{GEN} =10 Ω , I_{D} =20A		40		115
T _f	Fall Time			15		
C _{iss}	Input Capacitance			4800		
C _{oss}	Output Capacitance	V_{DS} =30V , V_{GS} =0V , F=1MHz		1370		pF
C _{rss}	Reverse Transfer Capacitance			65		
R_{g}	Gate Resistance	V _{DS} =0V , V _{GS} =0V , F=1MHz		1.8		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current				81	А
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A , V _R =30V ,		65		nS
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/us		78		nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

3. Guaranteed by design, not subject to production testing.



Characteristics Curves

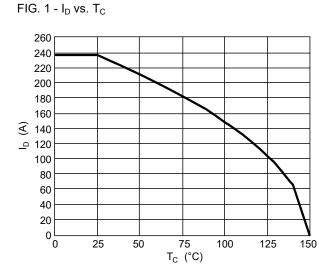


FIG. 3 - $R_{DS(ON)}$ vs. V_{GS}

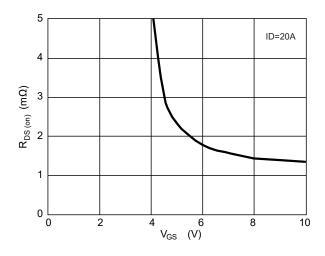


FIG. 5 - Normalized $R_{DS(ON)}$ vs. T_J

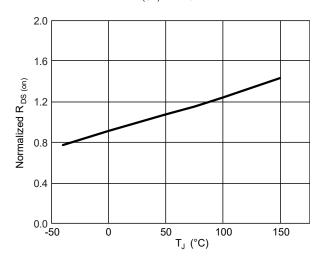


FIG. 2 -Transfer Characteristics

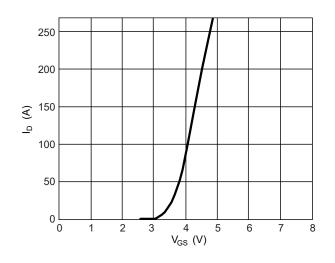


FIG. 4 - Gate Charge Characteristics

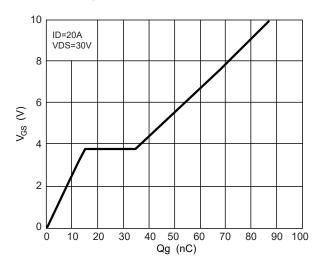
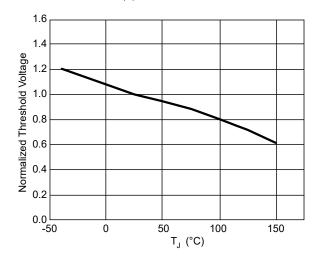


FIG. 6 - Normalized $V_{GS(th)}$ vs. T_J





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Characteristics Curves

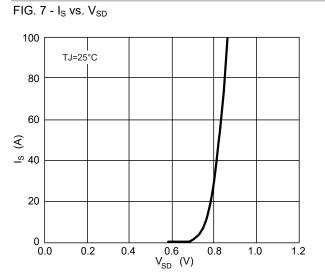
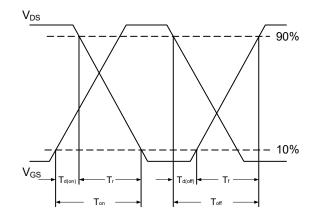
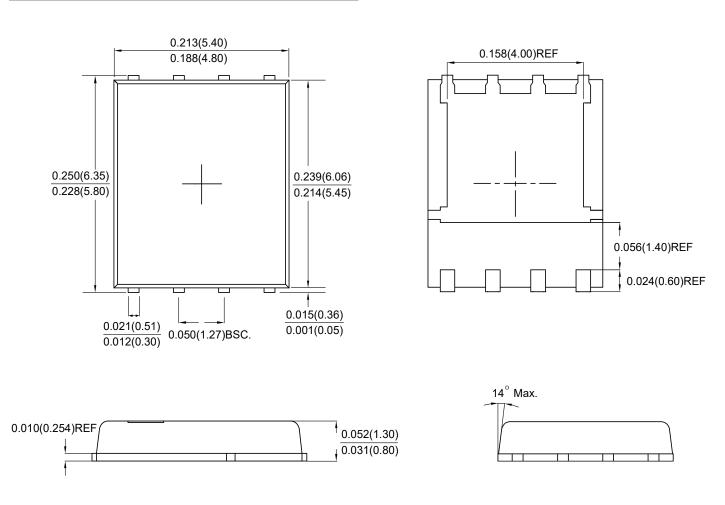


FIG. 8 - Switching Time Waveform



Package Outline Dimensions



PPAK5X6 Dimensions in inches and (millimeters)

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